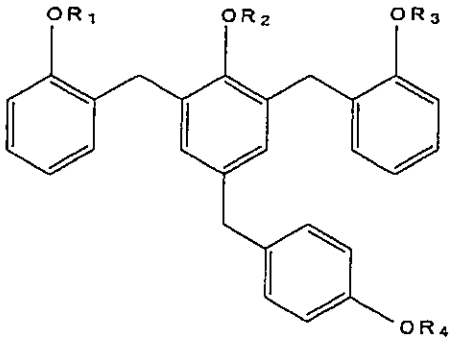
EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR ENCAPSULATION AND SEMICONDUCTOR DEVICE OBTAINED USING THE SAME

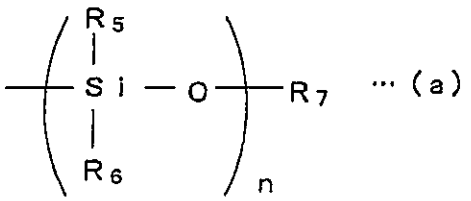
ABSTRACT OF THE DISCLOSURE

The present invention relates to an epoxy resin composition for semiconductor encapsulation, including the following components (A) to (E): (A) an epoxy resin; (B) a phenol resin other than the following component (C); (C) a silane-modified phenol resin represented by Formula (1) in which R_1 to R_4 may be the same or different from each other and are each independently a hydrogen atom or a monovalent functional group represented by Formula (a), provided that at least two of R_1 to R_4 are hydrogen atoms and at least one of the others is the functional group represented by Formula (a) in which R_5 is an alkoxyl group, R_6 is an alkoxyl or alkyl group, R_7 is an alkyl group, and n is an integer of from 1 to 50; (D) a curing accelerator; and (E) an inorganic filler, in which the component (C) is contained in an amount of 0.8 to 30.0% by weight based on a total weight of organic components in the epoxy resin composition:



... (1)

,



... (a)